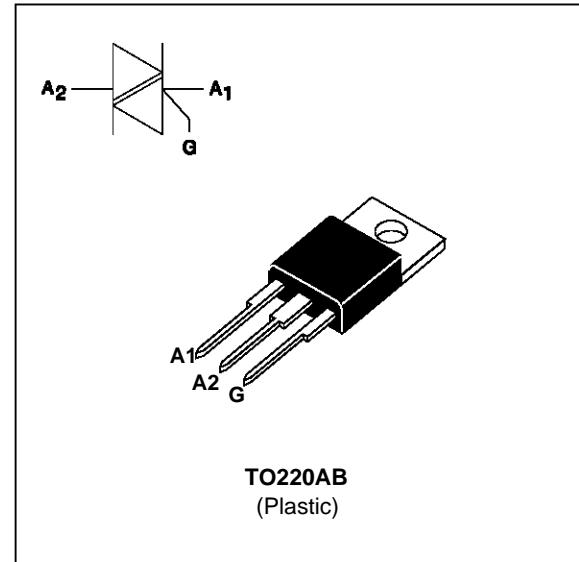




ALTERNISTORS

FEATURES

- VERY HIGH COMMUTATION : > 28 A/ms (400Hz)
- INSULATING VOLTAGE = 2500V(RMS) (UL RECOGNIZED : E81734)
- dV/dt : 500 V/ μ s min



DESCRIPTION

The TXDV 408 ---> 808 use a high performance passivated glass alternistor technology. Featuring very high commutation levels and high surge current capability, this family is well adapted to power control on inductive load (motor, transformer...)

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
I _T (RMS)	RMS on-state current (360° conduction angle)	8	A
I _{TSM}	Non repetitive surge peak on-state current (T _j initial = 25°C)	tp = 2.5 ms	115
		tp = 8.3 ms	85
		tp = 10 ms	80
I _{2t}	I _{2t} value	tp = 10 ms	A _{2s}
dI/dt	Critical rate of rise of on-state current Gate supply : I _G = 500mA diG/dt = 1A/ μ s	Repetitive F = 50 Hz	20
		Non Repetitive	100
T _{stg} T _j	Storage and operating junction temperature range	- 40 to + 150 - 40 to + 125	°C °C
T _I	Maximum lead temperature for soldering during 10 s at 4.5 mm from case	260	°C

Symbol	Parameter	TXDV			Unit
		408	608	808	
V _{DRM} V _{RRM}	Repetitive peak off-state voltage T _j = 125 °C	400	600	800	V

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R _{th} (j-a)	Junction to ambient	60	°C/W
R _{th} (j-c) DC	Junction to case for DC	4	°C/W
R _{th} (j-c) AC	Junction to case for 360° conduction angle (F= 50 Hz)	3	°C/W

GATE CHARACTERISTICS (maximum values)

P_G (AV) = 1W P_{GM} = 10W (tp = 20 μs) I_{GM} = 4A (tp = 20 μs) V_{GM} = 16V (tp = 20 μs).

ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions	Quadrant		Value	Unit
I _{GT}	V _D =12V (DC) R _L =33Ω	T _j =25°C	I-II-III	MAX	100 mA
V _{GT}	V _D =12V (DC) R _L =33Ω	T _j =25°C	I-II-III	MAX	1.5 V
V _{GD}	V _D =V _{DRM} R _L =3.3kΩ	T _j =110°C	I-II-III	MIN	0.2 V
t _{gt}	V _D =V _{DRM} I _G = 500mA dI _G /dt = 3A/μs	T _j =25°C	I-II-III	TYP	2.5 μs
I _L	I _G =1.2 I _{GT}	T _j =25°C	I-III	100 mA	
			II	200	
I _H *	I _T = 500mA gate open	T _j =25°C		MAX	100 mA
V _{TM} *	I _{TM} = 11A tp= 380μs	T _j =25°C		MAX	1.8 V
I _{DRM} I _{RRM}	V _{DRM} Rated V _{RRM} Rated	T _j =25°C T _j =110°C		MAX	0.01 mA
dV/dt *	Linear slope up to V _D =67%V _{DRM} gate open	T _j =110°C		MIN	500 V/μs
(dI/dt)c *	(dV/dt)c = 200V/μs (dV/dt)c = 10V/μs	T _j =110°C		MIN	7 A/ms
					28

* For either polarity of electrode A₂ voltage with reference to electrode A₁.

Fig.1 : Maximum RMS power dissipation versus RMS on-state current ($F=50\text{Hz}$).
(Curves are cut off by $(dI/dt)c$ limitation)

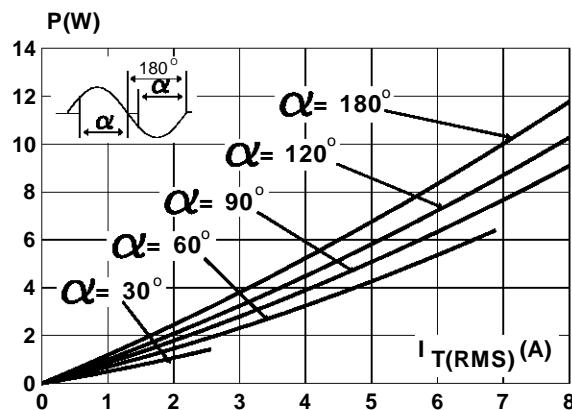
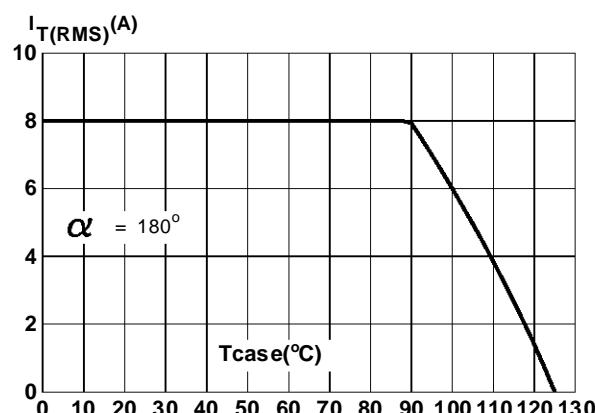
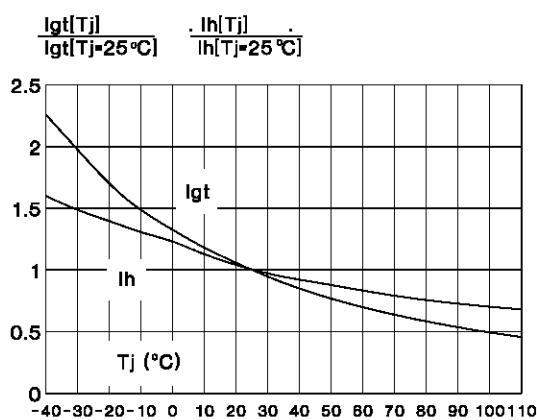
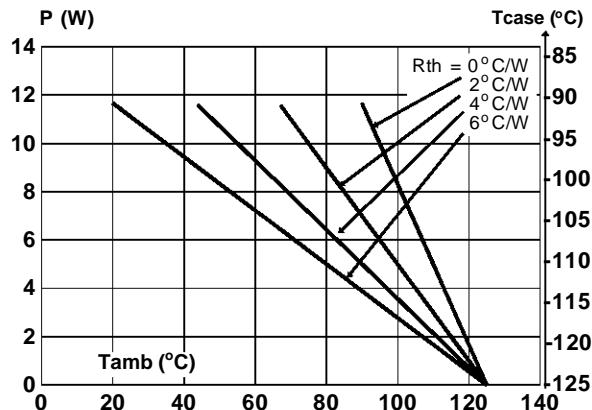
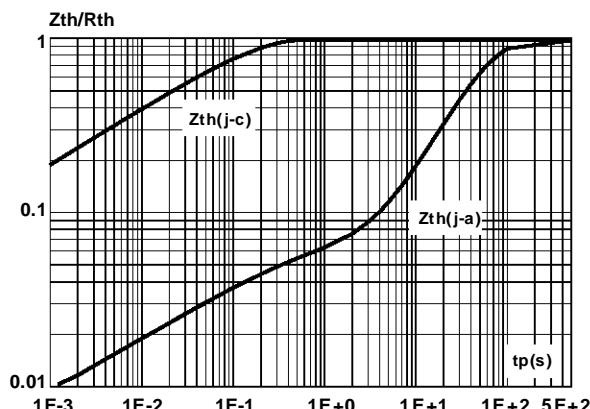
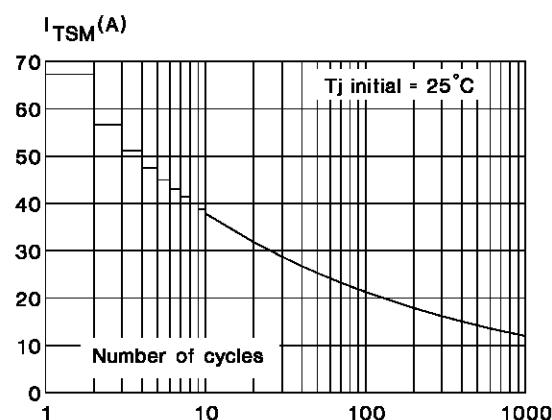
**Fig.3** : RMS on-state current versus case temperature.**Fig.5** : Relative variation of gate trigger current and holding current versus junction temperature.

Fig.2 : Correlation between maximum RMS power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact.

**Fig.4** : Relative variation of thermal impedance versus pulse duration.**Fig.6** : Non Repetitive surge peak on-state current versus number of cycles.

TXDV 408 --> 808

Fig.7 : Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10\text{ms}$, and corresponding value of I^2t .

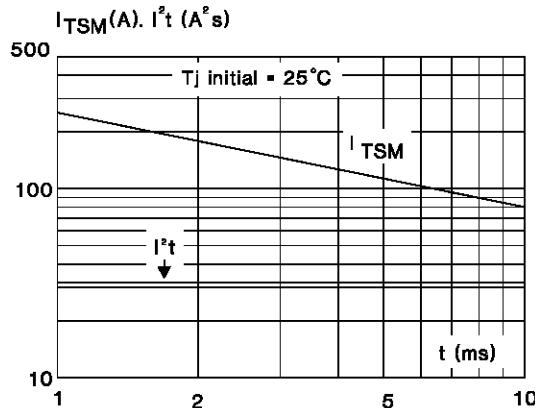


Fig.8 : On-state characteristics (maximum values).

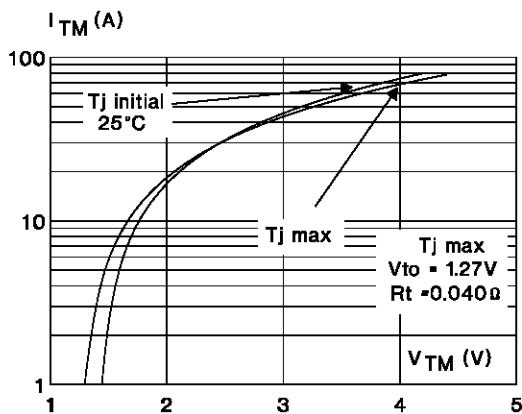
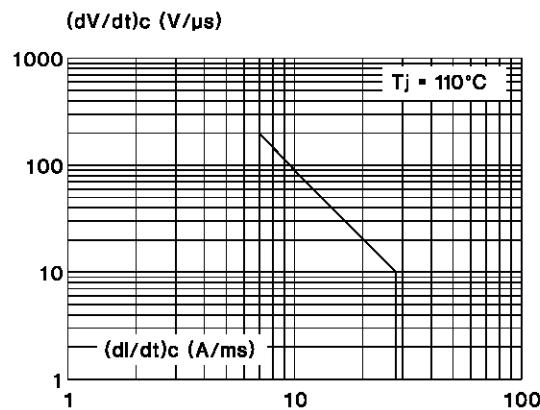
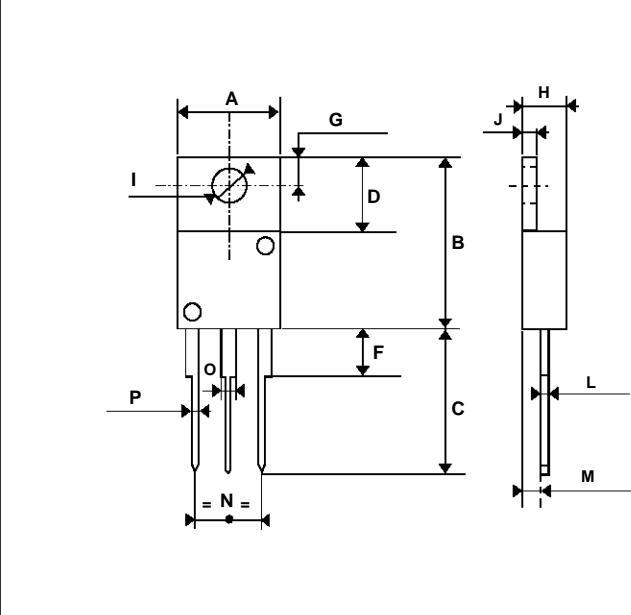


Fig.9 : Safe operating area.



PACKAGE MECHANICAL DATA

TO220AB Plastic



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	10.20	10.50	0.401	0.413
B	14.23	15.87	0.560	0.625
C	12.70	14.70	0.500	0.579
D	5.85	6.85	0.230	0.270
F		4.50		0.178
G	2.54	3.00	0.100	0.119
H	4.48	4.82	0.176	0.190
I	3.55	4.00	0.140	0.158
J	1.15	1.39	0.045	0.055
L	0.35	0.65	0.013	0.026
M	2.10	2.70	0.082	0.107
N	4.58	5.58	0.18	0.22
O	0.80	1.20	0.031	0.048
P	0.64	0.96	0.025	0.038

Cooling method : C

Marking : type number

Weight: 2.3 g

Recommended torque value : 0.8 m.N.

Maximum torque value : 1 m.N.

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